

N-Channel 650 V (D-S) Super Junction MOSFET

| PRODUCT SUMMARY | | |
|---|-----------------|------|
| V_{DS} (V) at T_J max. | 650 | |
| $R_{DS(on)}$ max. (Ω) at 25 °C | $V_{GS} = 10$ V | 0.19 |
| Q_g max. (nC) | 106 | |
| Q_{gs} (nC) | 14 | |
| Q_{gd} (nC) | 33 | |
| Configuration | Single | |

FEATURES

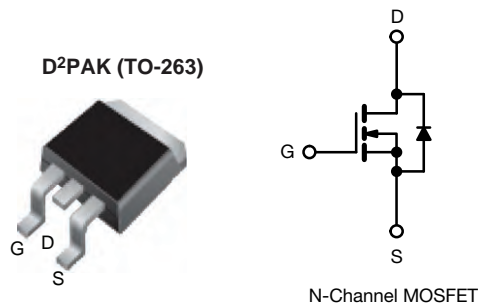
- Reduced t_{rr} , Q_{rr} , and I_{RRM}
- Low figure-of-merit (FOM) $R_{on} \times Q_g$
- Low input capacitance (C_{iss})
- Low switching losses due to reduced Q_{rr}
- Ultra low gate charge (Q_g)
- Avalanche energy rated (UIS)



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APPLICATIONS

- Telecommunications
 - Server and telecom power supplies
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Consumer and computing
 - ATX power supplies
- Industrial
 - Welding
 - Battery chargers
- Renewable energy
 - Solar (PV inverters)
- Switch mode power supplies (SMPS)




| ABSOLUTE MAXIMUM RATINGS ($T_C = 25$ °C, unless otherwise noted) | | | |
|---|------------------|----------------|------|
| PARAMETER | SYMBOL | LIMIT | UNIT |
| Drain-Source Voltage | V_{DS} | 650 | V |
| Gate-Source Voltage | V_{GS} | ± 30 | |
| Continuous Drain Current ($T_J = 150$ °C) | V_{GS} at 10 V | $T_C = 25$ °C | 20 |
| | | $T_C = 100$ °C | 13 |
| Pulsed Drain Current ^a | I_{DM} | 60 | A |
| Linear Derating Factor | | 1.7 | W/°C |
| Single Pulse Avalanche Energy ^b | E_{AS} | 367 | mJ |
| Maximum Power Dissipation | P_D | 208 | W |
| Operating Junction and Storage Temperature Range | T_J, T_{stg} | -55 to +150 | °C |
| Drain-Source Voltage Slope | dV/dt | $T_J = 125$ °C | 37 |
| Reverse Diode dV/dt ^d | | 31 | |
| Soldering Recommendations (Peak Temperature) ^c | for 10 s | 300 | °C |

Notes

- Repetitive rating; pulse width limited by maximum junction temperature.
- $V_{DD} = 50$ V, starting $T_J = 25$ °C, $L = 28.2$ mH, $R_g = 25$ Ω , $I_{AS} = 5.1$ A.
- 1.6 mm from case.
- $I_{SD} \leq I_D$, $dI/dt = 100$ A/ μ s, starting $T_J = 25$ °C.

| THERMAL RESISTANCE RATINGS | | | | |
|----------------------------------|------------|------|------|------|
| PARAMETER | SYMBOL | TYP. | MAX. | UNIT |
| Maximum Junction-to-Ambient | R_{thJA} | - | 62 | °C/W |
| Maximum Junction-to-Case (Drain) | R_{thJC} | - | 0.5 | |

| SPECIFICATIONS ($T_J = 25\text{ }^\circ\text{C}$, unless otherwise noted) | | | | | | | |
|---|---------------------|---|--|------|------|-----------|---------------|
| PARAMETER | SYMBOL | TEST CONDITIONS | | MIN. | TYP. | MAX. | UNIT |
| Static | | | | | | | |
| Drain-Source Breakdown Voltage | V_{DS} | $V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$ | | 650 | - | - | V |
| V_{DS} Temperature Coefficient | $\Delta V_{DS}/T_J$ | Reference to $25\text{ }^\circ\text{C}, I_D = 1\text{ mA}$ | | - | 0.67 | - | V/°C |
| Gate-Source Threshold Voltage (N) | $V_{GS(th)}$ | $V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$ | | 2 | - | 4 | V |
| Gate-Source Leakage | I_{GSS} | $V_{GS} = \pm 20\text{ V}$ | | - | - | ± 100 | nA |
| | | $V_{GS} = \pm 30\text{ V}$ | | - | - | ± 1 | μA |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{DS} = 520\text{ V}, V_{GS} = 0\text{ V}$ | | - | - | 1 | μA |
| | | $V_{DS} = 520\text{ V}, V_{GS} = 0\text{ V}, T_J = 125\text{ }^\circ\text{C}$ | | - | - | 500 | |
| Drain-Source On-State Resistance | $R_{DS(on)}$ | $V_{GS} = 10\text{ V}$ | $I_D = 11\text{ A}$ | - | 0.19 | - | Ω |
| Forward Transconductance | g_{fs} | $V_{DS} = 30\text{ V}, I_D = 11\text{ A}$ | | - | 7.0 | - | S |
| Dynamic | | | | | | | |
| Input Capacitance | C_{iss} | $V_{GS} = 0\text{ V},$ $V_{DS} = 100\text{ V},$ $f = 1\text{ MHz}$ | | - | 2322 | - | pF |
| Output Capacitance | C_{oss} | | | - | 105 | - | |
| Reverse Transfer Capacitance | C_{rss} | | | - | 4 | - | |
| Effective Output Capacitance, Energy Related ^a | $C_{o(er)}$ | $V_{DS} = 0\text{ V to } 520\text{ V}, V_{GS} = 0\text{ V}$ | | - | 84 | - | pF |
| Effective Output Capacitance, Time Related ^b | $C_{o(tr)}$ | | | - | 293 | - | |
| Total Gate Charge | Q_g | $V_{GS} = 10\text{ V}$ | $I_D = 11\text{ A}, V_{DS} = 520\text{ V}$ | - | 71 | 106 | nC |
| Gate-Source Charge | Q_{gs} | | | - | 14 | - | |
| Gate-Drain Charge | Q_{gd} | | | - | 33 | - | |
| Turn-On Delay Time | $t_{d(on)}$ | $V_{DD} = 520\text{ V}, I_D = 11\text{ A},$ $V_{GS} = 10\text{ V}, R_g = 9.1\text{ }\Omega$ | | - | 22 | 44 | ns |
| Rise Time | t_r | | | - | 34 | 68 | |
| Turn-Off Delay Time | $t_{d(off)}$ | | | - | 68 | 102 | |
| Fall Time | t_f | | | - | 42 | 84 | |
| Gate Input Resistance | R_g | $f = 1\text{ MHz}, \text{ open drain}$ | | - | 0.78 | - | Ω |
| Drain-Source Body Diode Characteristics | | | | | | | |
| Continuous Source-Drain Diode Current | I_S | MOSFET symbol showing the integral reverse p - n junction diode  | | - | - | 21 | A |
| Pulsed Diode Forward Current | I_{SM} | | | - | - | 53 | |
| Diode Forward Voltage | V_{SD} | $T_J = 25\text{ }^\circ\text{C}, I_S = 11\text{ A}, V_{GS} = 0\text{ V}$ | | - | 0.9 | 1.2 | V |
| Reverse Recovery Time | t_{rr} | $T_J = 25\text{ }^\circ\text{C}, I_F = I_S = 11\text{ A},$ $di/dt = 100\text{ A}/\mu\text{s}, V_R = 25\text{ V}$ | | - | 160 | - | ns |
| Reverse Recovery Charge | Q_{rr} | | | - | 1.2 | - | μC |
| Reverse Recovery Current | I_{RRM} | | | - | 14 | - | A |

Notes

- a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .
- b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

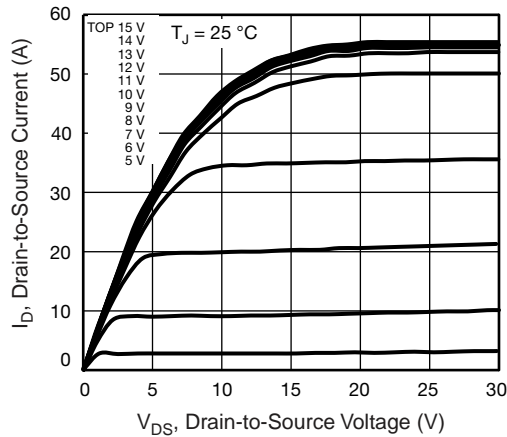


Fig. 1 - Typical Output Characteristics



Fig. 4 - Normalized On-Resistance vs. Temperature

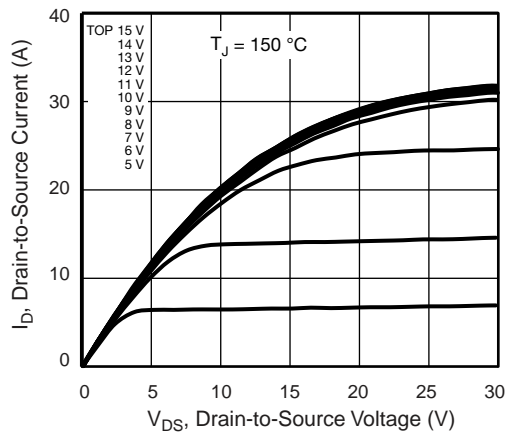


Fig. 2 - Typical Output Characteristics

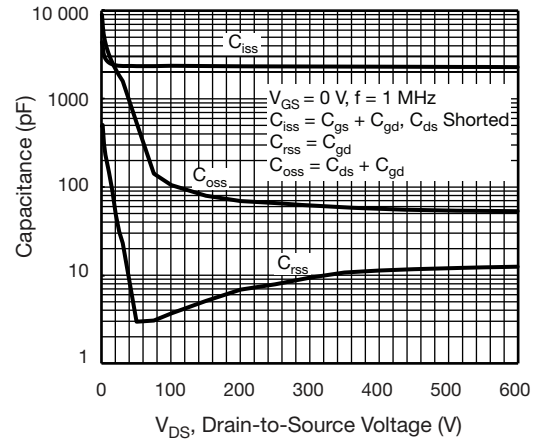


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage



Fig. 3 - Typical Transfer Characteristics

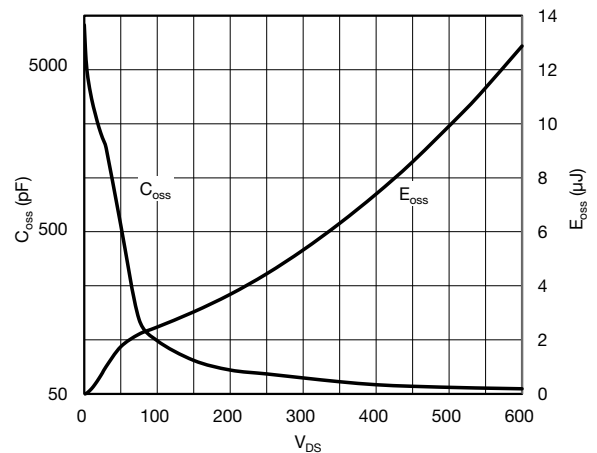


Fig. 6 - C_{oss} and E_{oss} vs. V_{DS}



Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage



Fig. 10 - Maximum Drain Current vs. Case Temperature



Fig. 8 - Typical Source-Drain Diode Forward Voltage



Fig. 11 - Temperature vs. Drain-to-Source Voltage



Fig. 9 - Maximum Safe Operating Area

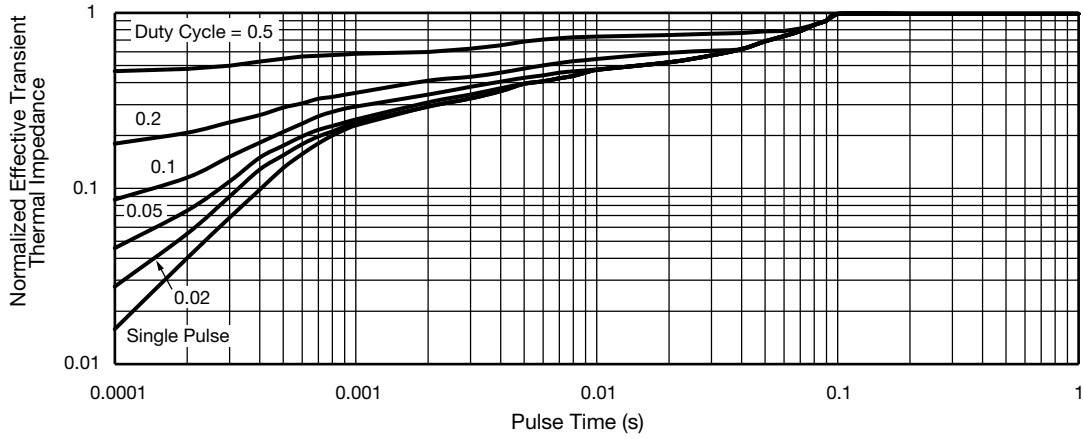


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case



Fig. 13 - Switching Time Test Circuit



Fig. 16 - Unclamped Inductive Waveforms

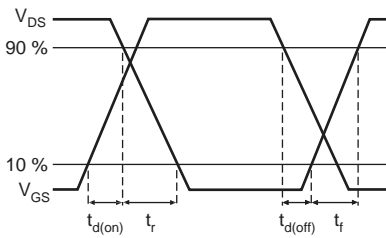


Fig. 14 - Switching Time Waveforms



Fig. 17 - Basic Gate Charge Waveform

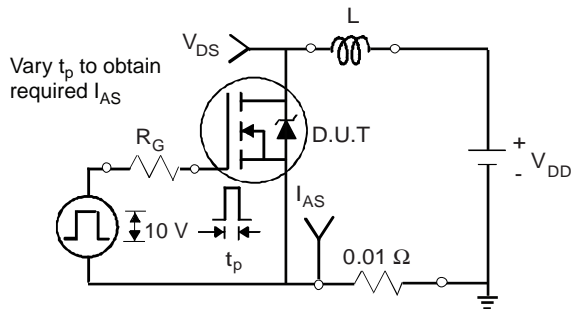
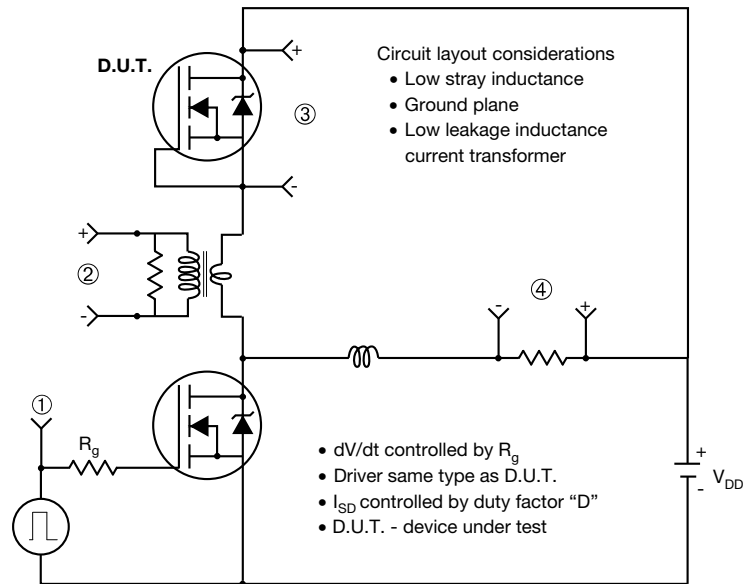


Fig. 15 - Unclamped Inductive Test Circuit



Fig. 18 - Gate Charge Test Circuit

Peak Diode Recovery dV/dt Test Circuit

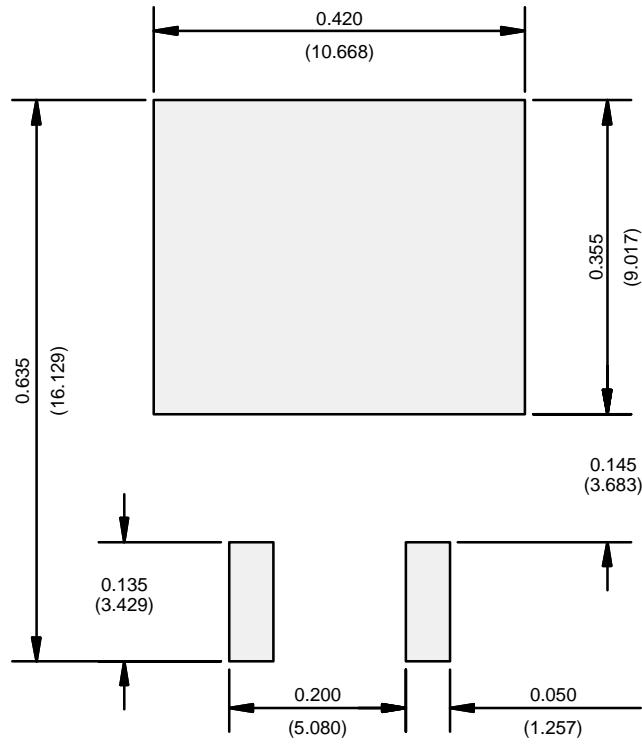


Note

a. $V_{GS} = 5 V$ for logic level devices

Fig. 19 - For N-Channel

RECOMMENDED MINIMUM PADS FOR D²PAK: 3-Lead



Recommended Minimum Pads
Dimensions in Inches/(mm)

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